



Tianjin Tianyuan Electronic Material Co.,Ltd.

HIGH MODULUS POLYIMIDE FILM TECHNICAL STANDARDS

High-modulus polyimide film is a kind of resin synthesized by a special formula.

The high-modulus polyimide film produced by biaxial stretching process not only has the excellent comprehensive properties of ordinary polyimide film, but also has higher modulus and mechanical strength, lower shrinkage and lower thermal expansion coefficient.

Application: Products can be widely used in high-end electronic industry, high-precision flexible printed circuit board, aerospace and other industries.

No.	Indicator Name		Unit	TY6052XE50 Performance index value
1	Appearance		/	The surface should be smooth and clean, and there should be no wrinkles, tears, particles, bubbles, pinholes, foreign impurities and other defects, and the edges should be neat and undamaged.
2	Thickness and allowable deviation		um	5
				±1
3	Tensile strength	Vertical	MPa	≥200
		Horizontal	MPa	≥200

4	Elongation at break	Vertical	%	≥25
		Horizontal	%	≥25
5	Young' s modulus of elasticity	Vertical	MPa	≥3500
		Horizontal	MPa	≥3500
6	Electrical strength	Average value	MV/m	≥220
		Individual values	MV/m	≥150
7	Thermal shrinkage	Vertical	%	≤0.15
	200°C, 30min			
8	Surface tension		dyn	≥52
9	Surface resistivity		Ω	≥1.0×10 ¹⁰
10	Volumetric resistivity		Ωm	≥1.0×10 ¹⁴